LM64 ±1°C Remote Diode Temperature Sensor with PWM Fan Control and 5 GPIO's

Check for Samples: LM64

FEATURES

- **Accurately Senses Remote and Local Diode Temperatures**
- **Integrated PWM Fan Speed Control Output**
- **Programmable 8-step Lookup Table for Quieting Fans**
- **$\overline{\text{ALERT}}$ and $\overline{\text{T_Crit}}$ Open-drain Outputs**
- **Tachometer Input for Measuring Fan RPM**
- **10 bit Plus Sign Remote Diode Temperature Data Format, with 0.125°C Resolution**
- **SMBus 2.0 Compatible Interface, Supports TIMEOUT**
- **5 General Purpose Input/Output pins**
- **5 General Purpose Default input pins**
- **24-pin WQFN Package**

APPLICATIONS

- **Computer Processor Thermal Management**
- **Graphics Processor Thermal Management**
- **Voltage Regulator Modules**
- **Electronic Instrumentation**
- **Power Supplies**
- **Projectors**

KEY SPECIFICATIONS

- **Remote Diode Temperature Accuracy (includes quantization error)**
  - **Ambient Temp**
    - **30°C to 50°C**
    - **0°C to 85°C**
  - **Diode Temp**
    - **120°C to 140°C**
    - **25°C to 140°C**
  - **Max Error**
    - **±1.0°C (max)**
    - **±3.0°C (max)**
- **Local Temp Accuracy (includes quantization error)**
  - **Ambient Temp 25°C to 125°C**
  - **Max Error ±3.0°C (max)**
- **Power Supply Requirements**
  - **Supply DC Voltage 3.0 V to 3.6 V**
  - **Supply DC Current 1.1 mA (typ)**

DESCRIPTION

The LM64 is a remote diode temperature sensor with PWM fan control. The LM64 accurately measures its own temperature and that of a remote diode. The LM64 remote temperature accuracy is factory trimmed for a MMBT3904 diode-connected transistor with a 16°C offset for high temperatures. $T_{ACTUAL\ DIODE\ JUNCTION} = T_{LM64} + 16°C$

The LM64 features a PWM, open-drain, fan control output, 5 GPIO (General Purpose Input/Output) and 5 GPD (General Purpose Default) pins. The 8-step Lookup Table allows for a non-linear fan speed vs. temperature transfer function often used to quiet acoustic fan noise.

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Connection Diagram

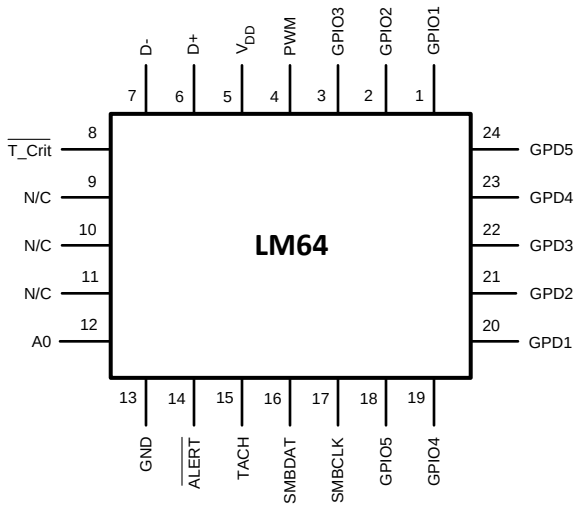

Figure 1. 24-pin WQFN Package

Pin Descriptions

Pin	Name	Input/Output	Function and Connection
1	GPIO1	Digital Input/ Open-Drain Output	General Purpose Open-Drain Digital Output or Digital Input. Typical pull-up resistor is 10 kΩ to V_{DD}.
2	GPIO2	Digital Input/ Open-Drain Output	General Purpose Open-Drain Digital Output or Digital Input. Typical pull-up resistor is 10 kΩ to V_{DD}.
3	GPIO3	Digital Input/ Open-Drain Output	General Purpose Open-Drain Digital Output or Digital Input. Typical pull-up resistor is 10 kΩ to V_{DD}.
4	PWM	Open-Drain Digital Output	Open-Drain Digital Output. Connect to fan drive circuitry. The power-on default for this pin is low (pin 4 pulled to ground).
5	V_{DD}	Power Supply Input	Connect to a low-noise +3.3 ± 0.3 VDC power supply, and bypass to GND with a 0.1 µF ceramic capacitor in parallel with a 100 pF ceramic capacitor. A bulk capacitance of 10 µF needs to be in the vicinity of the LM64's V_{DD} pin.
6	D+	Analog Input	Connect to the anode (positive side) of the remote diode. A 2.2 nF ceramic capacitor must be connected between pins 6 and 7.
7	D-	Analog Input	Connect to the cathode (negative side) of the remote diode. A 2.2 nF ceramic capacitor must be connected between pins 6 and 7.
8	$\overline{\text{T_Crit}}$	Open-Drain Digital Output	Open-Drain Digital Output. Typical pull-up resistor is 3 kΩ to V_{DD}.
9	N/C	N/A	No Connection.
10	N/C	N/A	No Connection.
11	N/C	N/A	No Connection.
12	A0	Digital Input	SMBus Address Select pin. If High, the SMBus address is 0x4E or, if Low, the SMBus address is 0x18. Typical pull-up resistor is 10 kΩ to V_{DD}.
13	GND	Ground	This is the analog and digital ground return.
14	$\overline{\text{ALERT}}$	Open-Drain Digital Output	This pin is an open-drain ALERT Output. Typical pull-up resistor is 3 kΩ to V_{DD}.
15	TACH	Digital Input	This pin is a digital tachometer input. Typical pull-up resistor is 3 kΩ to V_{DD}.
16	SMBDAT	Digital Input/ Open-Drain Output	This is the bi-directional SMBus data line. Typical pull-up resistor is 1.5 kΩ to V_{DD}.
17	SMBCLK	Digital Input	This is the SMBus clock input. Typical pull-up resistor is 1.5 kΩ to V_{DD}.
18	GPIO5	Digital Input/ Open-Drain Output	General Purpose Open-Drain Digital Output or Digital Input. Typical pull-up resistor is 10 kΩ to V_{DD}.

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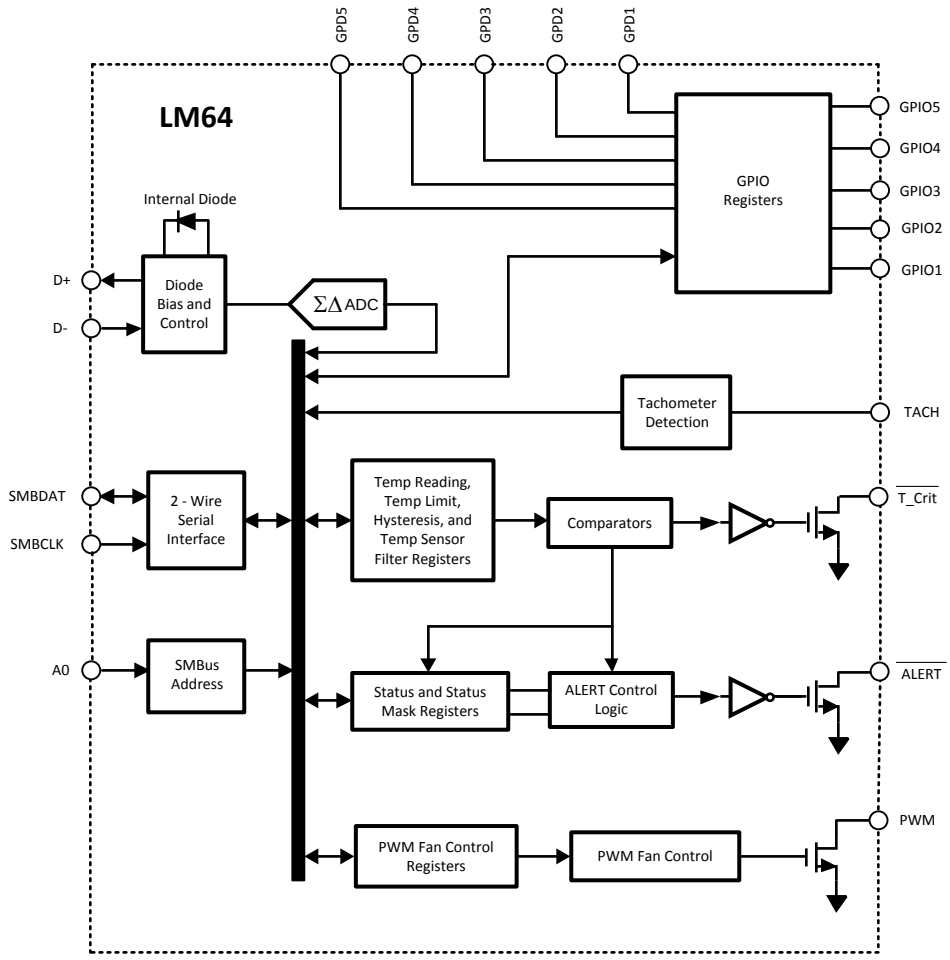
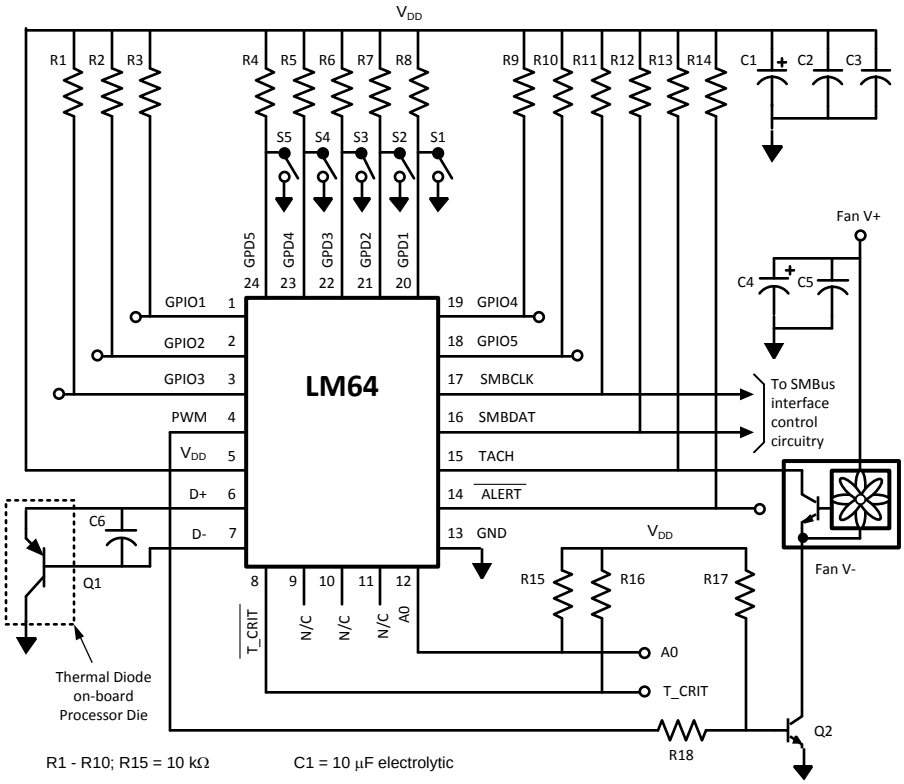
Pin Descriptions (continued)

Pin	Name	Input/Output	Function and Connection
19	GPIO4	Digital Input/ Open-Drain Output	General Purpose Open-Drain Digital Output or Digital Input. Typical pull-up resistor is 10 kΩ to V_{DD}.
20	GPD1	Digital Input	General Purpose Default Input Pin. Typical pull-up resistor is 10 kΩ to V_{DD}. Always connect to a logical High or Low level.
21	GPD2	Digital Input	General Purpose Default Input Pin. Typical pull-up resistor is 10 kΩ to V_{DD}. Always connect to a logical High or Low level.
22	GPD3	Digital Input	General Purpose Default Input Pin. Typical pull-up resistor is 10 kΩ to V_{DD}. Always connect to a logical High or Low level.
23	GPD4	Digital Input	General Purpose Default Input Pin. Typical pull-up resistor is 10 kΩ to V_{DD}. Always connect to a logical High or Low level.
24	GPD5	Digital Input	General Purpose Default Input Pin. Typical pull-up resistor is 10 kΩ to V_{DD}. Always connect to a logical High or Low level.

Simplified Block Diagram



Typical Application



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

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Absolute Maximum Ratings[1][2][3]

Supply Voltage, V_{DD}		−0.3 V to 6.0 V
Voltage on SMBDAT, SMBCLK, $\overline{\text{ALERT}}$, $\overline{\text{T_Crit}}$, PWM Pins		−0.5 V to 6.0 V
Voltage on Other Pins		−0.3 V to (V_{DD} + 0. 3 V)
Input Current, D− Pin		±1 mA
Input Current at All Other Pins [4]		5 mA
Package Input Current [4]		30 mA
Package Power Dissipation SMBDAT, $\overline{\text{ALERT}}$, $\overline{\text{T_Crit}}$, PWM pins		See [5]
Output Sink Current		10 mA
Storage Temperature		−65°C to +150°C
ESD Susceptibility[6]	Human Body Model	2000 V
	Machine Model	200 V
SMT Soldering Information See AN-1187 (SNOA401Q), "Leadless Leadframe Package" for information on SMT Assembly using LLP Packages.		

(1) All voltages are measured with respect to GND, unless otherwise noted.
(2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
(3) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.
(4) When the input voltage (V_{IN}) at any pin exceeds the power supplies (V_{IN} < GND or V_{IN} > V+), the current at that pin should be limited to 5 mA. Parasitic components and/or ESD protection circuitry are shown in the Table 1, for the LM64's pins, by an "X" when it exists. Care should be taken not to forward bias the parasitic diode, D1, present on pins D+ and D−. Doing so by more than 50 mV may corrupt temperature measurements.
(5) See AN-1187 SNOA401 for Thermal Resistance Junction-to-Ambient Temperature.
(6) Human body model, 100 pF discharged through a 1.5 kΩ resistor. Machine model, 200 pF discharged directly into each pin. See Figure 3 for the ESD Protection Input Structure.

Operating Ratings[1][2]

LM64 Operating Temperature Range	0°C ≤ T_A ≤ +85°C
Remote Diode Temperature Range	25°C ≤ T_D ≤ +140°C
Electrical Characteristics	T_{MIN} ≤ T_A ≤ T_{MAX}
Supply Voltage Range (V_{DD})	+3.0 V to +3.6 V

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
(2) All voltages are measured with respect to GND, unless otherwise noted.

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DC Electrical Characteristics

TEMPERATURE-TO-DIGITAL CONVERTER CHARACTERISTICS

The following specifications apply for V_{DD} = 3.0 VDC to 3.6 VDC, and all analog source impedance R_S = 50 Ω unless otherwise specified in the conditions. **Boldface limits apply for $T_A = T_{MIN}$ to T_{MAX};** all other limits T_A = +25°C.

Parameter	Conditions		Typical (1)	Limits (2)	Units (Limits)
Temperature Error using a diode-connected MMBT3904 transistor. T_D is the Remote Diode Junction Temperature. $T_D = T_{LM64} + 16°C$	T_A = +30°C to +50°C	T_D = +120°C to +140°C		**±1**	°C (max)
	T_A = +0°C to +85°C	T_D = +25°C to +140°C		**±3**	°C (max)
Temperature Error Using the Local Diode	T_A = +25°C to +125°C (3)		±1	**±3**	°C (max)
Remote Diode Resolution			11		Bits
			0.125		°C
Local Diode Resolution			8		Bits
			1		°C
Conversion Time of All Temperatures	Fastest Setting		31.25	**34.4**	ms (max)
D− Source Voltage			0.7		V
Diode Source Current	(V_{D+} − V_{D-}) = +0.65 V; High Current		160	**315**	µA (max)
				110	µA (min)
	Low Current		13	**20**	µA (max)
				7	µA (min)

(1) "Typicals" are at T_A = 25°C and represent most likely parametric norm. They are to be used as general reference values not for critical design calculations.
(2) Limits are guaranteed to TI's AOQL (Average Outgoing Quality Level).
(3) Local temperature accuracy does not include the effects of self-heating. The rise in temperature due to self-heating is the product of the internal power dissipation of the LM64 and the thermal resistance. See AN-1187 (SNOA401) for the thermal resistance to be used in the self-heating calculation.

Operating Electrical Characteristics

Parameter	Conditions			Typ (1)	Limits (2)	Units
$\overline{ALERT}$, $\overline{T_Crit}$ and PWM Output Saturation Voltage	$\overline{ALERT}$, $\overline{T_Crit}$		PWM			
	I_{OUT}	4 mA	6 mA		**0.4**	V (max)
	I_{OUT}	6 mA			**0.55**	
Power-On-Reset Threshold Voltage					**2.4**	V (max)
					1.8	V (min)
Supply Current (3)	SMBus Inactive, 16 Hz Conversion Rate			1.1	**2.0**	mA (max)
	STANDBY Mode			320		µA

(1) "Typicals" are at T_A = 25°C and represent most likely parametric norm. They are to be used as general reference values not for critical design calculations.
(2) Limits are guaranteed to TI's AOQL (Average Outgoing Quality Level).
(3) The supply current will not increase substantially with an SMBus transaction.

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AC Electrical Characteristics

The following specifications apply for V_{DD} = 3.0 VDC to 3.6 VDC, and all analog source impedance R_S = 50Ω unless otherwise specified in the conditions. **Boldface limits apply for $T_A = T_{MIN}$ to T_{MAX};** all other limits T_A= +25°C.

Symbol	Parameter	Conditions	Typical (1)	Limits (2)	Units (Limit)
TACHOMETER ACCURACY					
	Fan Control Accuracy			±10	% (max)
	Fan Full-Scale Count			65535	(max)
	Fan Counter Clock Frequency		90		kHz
	Fan Count Update Frequency		1.0		Hz
FAN PWM OUTPUT					
	Frequency Accuracy			±10	% (max)

(1) "Typicals" are at T_A = 25°C and represent most likely parametric norm. They are to be used as general reference values not for critical design calculations.
(2) Limits are guaranteed to TI's AOQL (Average Outgoing Quality Level).

Digital Electrical Characteristics

Symbol	Parameter	Conditions	Typical (1)	Limits (2)	Units (Limit)
V_{IH}	Logical High Input Voltage			**2.1**	V (min)
V_{IL}	Logical Low Input Voltage			**0.8**	V (max)
I_{IH}	Logical High Input Current	$V_{IN} = V_{DD}$	0.005	**+10**	µA (max)
I_{IL}	Logical Low Input Current	V_{IN} = GND	−0.005	**−10**	µA (max)
C_{IN}	Digital Input Capacitance		20		pF

(1) "Typicals" are at T_A = 25°C and represent most likely parametric norm. They are to be used as general reference values not for critical design calculations.
(2) Limits are guaranteed to TI's AOQL (Average Outgoing Quality Level).

SMBus Logical Electrical Characteristics

The following specifications apply for V_{DD} = 3.0 VDC to 3.6 VDC, and all analog source impedance R_S = 50 Ω unless otherwise specified in the conditions. **Boldface limits apply for $T_A = T_{MIN}$ to T_{MAX};** all other limits T_A = +25°C.

Symbol	Parameter	Conditions	Typical (1)	Limits (2)	Units (Limit)
SMBDAT OPEN-DRAIN OUTPUT					
V_{OL}	Logic Low Level Output Voltage	I_{OL} = 4 mA		**0.4**	V (max)
I_{OH}	High Level Output Current	$V_{OUT} = V_{DD}$	0.03	**10**	µA (max)
SMBDAT, SMBCLK INPUTS					
V_{IH}	Logical High Input Voltage			**2.1**	V (min)
V_{IL}	Logical Low Input Voltage			**0.8**	V (max)
V_{HYST}	Logic Input Hysteresis Voltage		400		mV

(1) "Typicals" are at T_A = 25°C and represent most likely parametric norm. They are to be used as general reference values not for critical design calculations.
(2) Limits are guaranteed to TI's AOQL (Average Outgoing Quality Level).

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SMBus Digital Switching Characteristics

Unless otherwise noted, these specifications apply for V_{DD} = +3.0 VDC to +3.6 VDC, C_L (load capacitance) on output lines = 80 pF. **Boldface limits apply for $T_A = T_J$; $T_{MIN} \le T_A \le T_{MAX}$;** all other limits $T_A = T_J$ = +25°C, unless otherwise noted. The switching characteristics of the LM64 fully meet or exceed the published specifications of the SMBus version 2.0. The following parameters are the timing relationships between SMBCLK and SMBDAT signals related to the LM64. They adhere to but are not necessarily the same as the SMBus bus specifications.

Symbol	Parameter	Conditions	Limits (1)	Units (Limit)
f_{SMB}	SMBus Clock Frequency		**10** **100**	kHz (min) kHz (max)
t_{LOW}	SMBus Clock Low Time	From $V_{IN(0)\ max}$ to $V_{IN(0)\ max}$	**4.7**	µs (min)
t_{HIGH}	SMBus Clock High Time	From $V_{IN(1)\ min}$ to $V_{IN(1)\ min}$	**4.0** **50**	µs (min) µs (max)
t_R	SMBus Rise Time	See (2)	**1**	µs (max)
t_F	SMBus Fall Time	See (3)	**0.3**	µs (max)
t_{OF}	Output Fall Time	C_L = 400 pF, I_O = 3 mA	**250**	ns (max)
$t_{TIMEOUT}$	SMBData and SMBCLK Time Low for Reset of Serial Interface See (4)		**25** **35**	ms (min) ms (max)
$t_{SU:DAT}$	Data In Setup Time to SMBCLK High		**250**	ns (min)
$t_{HD:DAT}$	Data Out Hold Time after SMBCLK Low		**300** **930**	ns (min) ns (max)
$t_{HD:STA}$	Hold Time after (Repeated) Start Condition. After this period the first clock is generated.		**4.0**	µs (min)
$t_{SU:STO}$	Stop Condition SMBCLK High to SMBDAT Low (Stop Condition Setup)		**100**	ns (min)
$t_{SU:STA}$	SMBus Repeated Start-Condition Setup Time, SMBCLK High to SMBDAT Low		**4.7**	µs (min)
t_{BUF}	SMBus Free Time between Stop and Start Conditions		**4.7**	µs (min)

(1) Limits are guaranteed to TI's AOQL (Average Outgoing Quality Level).
(2) The output rise time is measured from ($V_{IL\ max}$ - 0.15 V) to ($V_{IH\ min}$ + 0.15 V).
(3) The output fall time is measured from ($V_{IH\ min}$ + 0.15 V) to ($V_{IL\ min}$ - 0.15 V).
(4) Holding the SMBData and/or SMBCLK lines Low for a time interval greater than $t_{TIMEOUT}$ will reset the LM64's SMBus state machine, therefore setting SMBDAT and SMBCLK pins to a high impedance state.

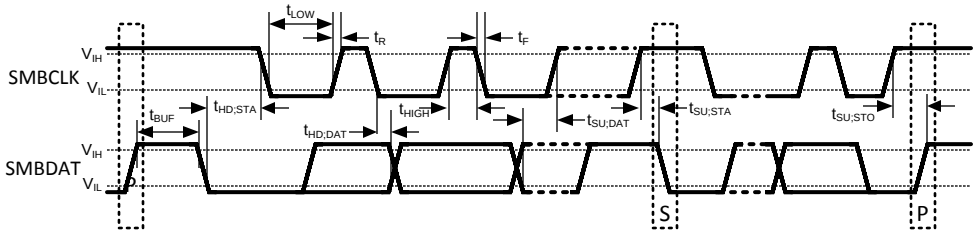

Figure 2. SMBus Timing Diagram for SMBCLK and SMBDAT Signals

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Table 1.

Pin Name	Pin #	D1	D2	D3	D4	D5	D6	R1	SNP	ESD CLAMP
GPIO1	1						X	X	X	
GPIO2	2						X	X	X	
GPIO3	3						X	X	X	
PWM	4						X	X	X	
V_{DD}	5									X
D+	6	X	X			X	X	X		X
D−	7	X	X		X	X	X			X
$\overline{T_Crit}$	8		X				X	X	X	
A0	12								X	
$\overline{ALERT}$	14		X				X	X	X	
TACH	15						X	X	X	
SMBDAT	16						X	X	X	
SMBCLK	17								X	
GPIO5	18						X	X	X	
GPIO4	19						X	X	X	
GPD1	20								X	
GPD2	21								X	
GPD3	22								X	
GPD4	23								X	
GPD5	24								X	

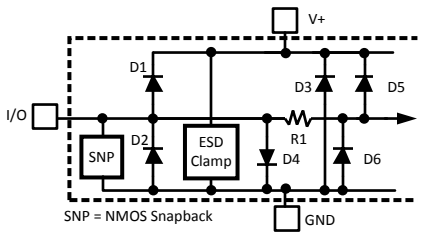

Figure 3. ESD Protection Input Structure

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FUNCTIONAL DESCRIPTION

The LM64 Remote Diode Temperature Sensor with Integrated Fan Control incorporates a ΔV_{BE}-based temperature sensor using a Local or Remote diode and a 10-bit plus sign ΔΣ ADC (Delta-Sigma Analog-to-Digital Converter). The pulse-width modulated (PWM) open-drain output, with a pull-up resistor, can drive a switching transistor to modulate the fan. The LM64 can measure the fan speed on the pulses from the fan's open-collector tachometer output, pulled up by a 1.5 kΩ resistor to V_{DD}. The ALERT open-drain output will be pulled low under certain conditions descibed in the sections below. The T_Crit open-drain output will be pulled low when the T_Crit setpoint temperature limit is exceeded. This behaves as a typical comparator function without any latching.

The LM64's two-wire interface is compatible with the SMBus Specification 2.0 . For more information the reader is directed to www.smbus.org.

In the LM64, digital comparators are used to compare the measured Local Temperature (LT) to the Local High Setpoint user-programmable temperature limit register. The measured Remote Temperature (RT) is digitally compared to the Remote High Setpoint (RHS), the Remote Low Setpoint (RLS), and the Remote T_CRIT Setpoint (RCS) user-programmable temperature limits. An ALERT output will occur when the measured temperature is: (1) higher than either the High Setpoint or the T_CRIT Setpoint, or (2) lower than the Low Setpoint. The ALERT Mask register allows the user to prevent the generation of these ALERT outputs.

The temperature hysteresis is set by the value placed in the Hysteresis Register (TH).

The LM64 may be placed in a low power Standby mode by setting the Standby bit found in the Configuration Register. In the Standby mode continuous conversions are stopped. In Standby mode the user may choose to allow the PWM output signal to continue, or not, by programming the PWM Disable in Standby bit in the Configuration Register.

The Local Temperature reading and setpoint data registers are 8-bits wide. The format of the 11-bit remote temperature data is a 16-bit left justified word. Two 8-bit registers, high and low bytes, are provided for each setpoint as well as the temperature reading. Two Remote Temperature Offset (RTO) Registers: High Byte and Low Byte (RTOHB and RTOLB) may be used to correct the temperature readings by adding or subtracting a fixed value based on a different non-ideality factor of the thermal diode if different from the graphics processor thermal diode. See Diode Non_Ideality.

CONVERSION SEQUENCE

The LM64 takes approximately 31.25 ms to convert the Local Temperature (LT), Remote Temperature (RT), and to update all of its registers. The Conversion Rate may be modified using the Conversion Rate Register. When the conversion rate is modified a delay is inserted between conversions, the actual conversion time remains at 31.25 ms. Different Conversion Rates will cause the LM64 to draw different amounts of supply current as shown in Figure 4.

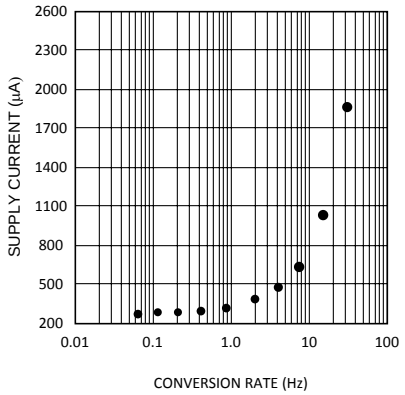

Figure 4. Supply Current vs Conversion Rate

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THE $\overline{\text{ALERT}}$ OUTPUT

When the ALERT Mask bit in the Configuration register is written as zero the ALERT interrupts are enabled.

The LM64's $\overline{\text{ALERT}}$ pin is versatile and can produce three different methods of use to best serve the system designer: (1) as a temperature comparator (2) as a temperature-based interrupt flag, and (3) as part of an SMBus ALERT System. The three methods of use are further described below. The ALERT and interrupt methods are different only in how the user interacts with the LM64.

The remote temperature (RT) reading is associated with a T_CRIT Setpoint Register, and both local and remote temperature (LT and RT) readings are associated with a HIGH setpoint register (LHS and RHS). The RT is also associated with a LOW setpoint register (RLS). At the end of every temperature reading a digital comparison determines whether that reading is above its HIGH or T_CRIT setpoint or below its LOW setpoint. If so, the corresponding bit in the ALERT Status Register is set. If the ALERT mask bit is low, any bit set in the ALERT Status Register, with the exception of Busy or Open, will cause the $\overline{\text{ALERT}}$ output to be pulled low. Any temperature conversion that is out of the limits defined in the temperature setpoint registers will trigger an ALERT. Additionally, the ALERT Mask Bit must be cleared to trigger an ALERT in all modes.

The three different ALERT modes will be discussed in the following sections.

$\overline{\text{ALERT}}$ Output as a Temperature Comparator

When the LM64 is used in a system in which does not require temperature-based interrupts, the $\overline{\text{ALERT}}$ output could be used as a temperature comparator. In this mode, once the condition that triggered the $\overline{\text{ALERT}}$ to go low is no longer present, the $\overline{\text{ALERT}}$ is negated (Figure 5). For example, if the $\overline{\text{ALERT}}$ output was activated by the comparison of LT > LHS, when this condition is no longer true, the $\overline{\text{ALERT}}$ will return HIGH. This mode allows operation without software intervention, once all registers are configured during set-up. In order for the $\overline{\text{ALERT}}$ to be used as a temperature comparator, the Comparator Mode bit in the Remote Diode Temperature Filter and Comparator Mode Register must be asserted. This is not the power-on default state.

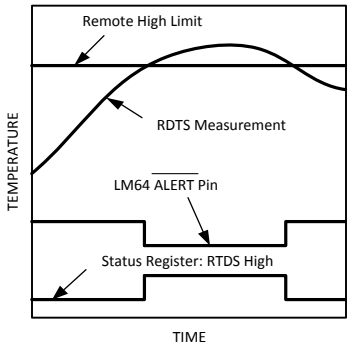

Figure 5. $\overline{\text{ALERT}}$ Output as Temperature Comparator Response Diagram

$\overline{\text{ALERT}}$ Output as an Interrupt

The LM64's $\overline{\text{ALERT}}$ output can be implemented as a simple interrupt signal when it is used to trigger an interrupt service routine. In such systems it is desirable for the interrupt flag to repeatedly trigger during or before the interrupt service routine has been completed. Under this method of operation, during the read of the ALERT Status Register the LM64 will set the ALERT Mask bit in the Configuration Register if any bit in the ALERT Status Register is set, with the exception of Busy and Open. This prevents further $\overline{\text{ALERT}}$ triggering until the master has reset the ALERT Mask bit, at the end of the interrupt service routine. The ALERT Status Register bits are cleared only upon a read command from the master (see Figure 5) and will be re-asserted at the end of the next conversion if the triggering condition(s) persist(s). In order for the $\overline{\text{ALERT}}$ to be used as a dedicated interrupt signal, the Comparator Mode bit in the Remote Diode Temperature Filter and Comparator Mode Register must be set low. This is the power-on default state. The following sequence describes the response of a system that uses the $\overline{\text{ALERT}}$ output pin as an interrupt flag:

1. Master senses $\overline{\text{ALERT}}$ low.
2. Master reads the LM64 ALERT Status Register to determine what caused the ALERT.
3. LM64 clears ALERT Status Register, resets the $\overline{\text{ALERT}}$ HIGH and sets the ALERT Mask bit in the

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Configuration Register.

4. Master attends to conditions that caused the $\overline{\text{ALERT}}$ to be triggered. The fan is started, setpoint limits are adjusted, etc.
5. Master resets the ALERT Mask bit in the Configuration Register.

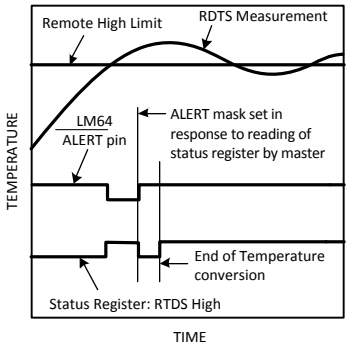

Figure 6. $\overline{\text{ALERT}}$ Output as an Interrupt Temperature Response Diagram

$\overline{\text{ALERT}}$ Output as an SMBus ALERT

An SMBus alert line is created when the $\overline{\text{ALERT}}$ output is connected to: (1) one or more $\overline{\text{ALERT}}$ outputs of other SMBus compatible devices, and (2) to a master. Under this implementation, the LM64's $\overline{\text{ALERT}}$ should be operated using the ARA (Alert Response Address) protocol. The SMBus 2.0 ARA protocol, defined in the SMBus specification 2.0, is a procedure designed to assist the master in determining which part generated an interrupt and to service that interrupt.

The SMBus alert line is connected to the open-drain ports of all devices on the bus, thereby AND'ing them together. The ARA method allows the SMBus master, with one command, to identify which part is pulling the SMBus alert line LOW. It also prevents the part from pulling the line LOW again for the same triggering condition. When an ARA command is received by all devices on the bus, the devices pulling the SMBus alert line LOW: (1) send their address to the master and (2) release the SMBus alert line after acknowledgement of their address.

The SMBus Specifications 1.1 and 2.0 state that in response to and ARA (Alert Response Address) “after acknowledging the slave address the device must disengage its ALERT pulldown”. Furthermore, “if the host still sees ALERT low when the message transfer is complete, it knows to read the ARA again.” This SMBus “disengaging ALERT requirement prevents locking up the SMBus alert line. Competitive parts may address the “disengaging of ALERT” differently than the LM64 or not at all. SMBus systems that implement the ARA protocol as suggested for the LM64 will be fully compatible with all competitive parts.

The LM64 fulfills “disengaging of ALERT” by setting the ALERT Mask Bit in the Configuration Register after sending out its address in response to an ARA and releasing the $\overline{\text{ALERT}}$ output pin. Once the ALERT Mask bit is activated, the $\overline{\text{ALERT}}$ output pin will be disabled until enabled by software. In order to enable the ALERT the master must read the ALERT Status Register, during the interrupt service routine and then reset the ALERT Mask bit in the Configuration Register to 0 at the end of the interrupt service routine.

The following sequence describes the ARA response protocol.

1. Master senses SMBus alert line low
2. Master sends a START followed by the Alert Response Address (ARA) with a Read Command.
3. Alerting Device(s) send ACK.
4. Alerting Device(s) send their address. While transmitting their address, alerting devices sense whether their address has been transmitted correctly. (The LM64 will reset its $\overline{\text{ALERT}}$ output and set the ALERT Mask bit once its complete address has been transmitted successfully.)
5. Master/slave NoACK
6. Master sends STOP
7. Master attends to conditions that caused the ALERT to be triggered. The ALERT Status Register is read and fan started, setpoints adjusted, etc.

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8. Master resets the ALERT Mask bit in the Configuration Register.

The ARA, 000 1100, is a general call address. No device should ever be assigned to this address.

The ALERT Configuration bit in the Remote Diode Temperature Filter and Comparator Mode Register must be set low in order for the LM64 to respond to the ARA command.

The $\overline{\text{ALERT}}$ output can be disabled by setting the ALERT Mask bit in the Configuration Register. The power-on default is to have the ALERT Mask bit and the ALERT Configuration bit low.

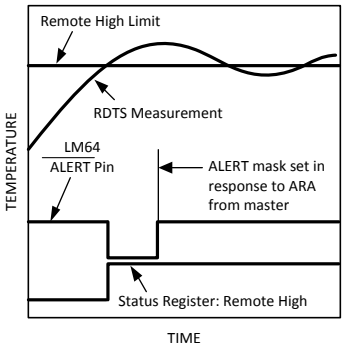

Figure 7. $\overline{\text{ALERT}}$ Output as an SMBus ALERT Temperature Response Diagram

SMBus INTERFACE

Since the LM64 operates as a slave on the SMBus, the SMBCLK line is an input and the SMBDAT line is bi-directional. The LM64 never drives the SMBCLK line and it does not support clock stretching. The LM64 has two hardware-selectable 7-bit slave addresses. The user may input a logical High or Low on the A0 Address pin to select one of the two pre-programmed SMBus slave addresses. The options are as follows:

A0 Pin	SMBus Address 0x[Hex]	SMBus Slave Address Bits						
		A6	A5	A4	A3	A2	A1	A0
0	18	0	0	1	1	0	0	0
1	4E	1	0	0	1	1	1	0

POWER-ON RESET (POR) DEFAULT STATES

For information on the POR default states see LM64 REGISTER MAP IN FUNCTIONAL ORDER.

TEMPERATURE DATA FORMAT

Temperature data can only be read from the Local and Remote Temperature registers. The High, Low and T_CRIT setpoint registers are Read/Write.

Remote temperature data is represented by an 11-bit, two's complement word with a Least Significant Bit (LSB) equal to 0.125°C. The data format is a left justified 16-bit word available in two 8-bit registers. Some examples of temperature conversions are shown below.

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Table 2. Actual vs. LM64 Remote Temperature Conversion(1)

Actual Remote Diode Temperature,°C	LM64 Remote Diode Temperature Register, °C	Binary Results in LM64 Remote Temperature Register	Hex Remote Temperature Register
120	+104	0110 1000 0000 0000	6800h
125	+109	0110 1101 0000 0000	6D00h
126	+110	0110 1110 0000 0000	6E00h
130	+114	0111 0010 0010 0000	7200h
135	+119	0111 0111 0000 0000	7700h
140	+124	0111 1100 0000 0000	7C00h

(1) Output is 11-bit two's complement word. LSB = 0.125 °C.

Table 3. Actual vs. Remote T_Crit Setpoint Example

Actual Remote Diode T_Crit Setpoint,°C	Remote T_CRIT High Setpoint, °C	Binary Remote T_CRIT High Setpoint Value	Hex Remote T_CRIT High Setpoint Value
126	+110	0110 1110	6Eh

Local Temperature data is represented by an 8-bit, two's complement byte with an LSB equal to 1°C:

Temperature	Digital Output	
	Binary	Hex
+125°C	0111 1101	7D
+25°C	0001 1001	19
+1°C	0000 0001	01
0°C	0000 0000	00
−1°C	1111 1111	FF
−25°C	1110 0111	E7
−55°C	1100 1001	C9

OPEN-DRAIN OUTPUTS, INPUTS, AND PULL-UP RESISTORS

The SMBDAT, $\overline{\text{ALERT}}$, $\overline{\text{T_Crit}}$, GPIO and PWM open-drain outputs and the GPD, TACH, and A0 inputs are pulled-up by pull-up resistors to V_{DD}as suggested in the table below.

Pin Name	Pin Number	Suggested Pull-up Resistor	
		Range	Typical
SMBCLK	17	1 kΩ to 2 kΩ	1.5 kΩ
SMBDAT	16	1 kΩ to 2 kΩ	1.5 kΩ
ALERT	14	1 kΩ to 5 kΩ	3 kΩ
T_Crit	8	1 kΩ to 5 kΩ	3 kΩ
A0	12	5 kΩ to 20 kΩ	10 kΩ
GPIOx	1-3;18,19	5 kΩ to 20 kΩ	10 kΩ
GPDx	20-24	5 kΩ to 20 kΩ	10 kΩ
PWM	4	See (1)	See (1)
TACH	15	1 kΩ to 5 kΩ	3 kΩ

(1) Depends on the fan drive circuitry connected to this pin. In the absence of fan control circuitry use a 1 kΩ pull-up resistor to V_{DD}.

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DIODE FAULT DETECTION

The LM64 can detect fault conditions caused by the remote diode. If the D+ pin is detected to be shorted to V_{DD}, or open: (1) the Remote Temperature High Byte (RTHB) register is loaded with 127°C, (2) the Remote Temperature Low Byte (RTLB) register is loaded with 0, and (3) the OPEN bit (D2) in the status register is set. Therefore, if the Remote T_CRIT setpoint register (RCS): (1) is set to a value less than +127°C and (2) the ALERT Mask is disabled, then the ALERT output pin will be pulled low. If the Remote High Setpoint High Byte (RHSHB) is set to a value less than +127°C and (2) the ALERT Mask is disabled, then the ALERT and T_Crit outputs will be pulled low. The OPEN bit by itself will not trigger an ALERT.

If the D+ pin is shorted to either ground or D−, then the Remote Temperature High Byte (RTHB) register is loaded with −128°C (1000 0000) and the OPEN bit in the ALERT Status Register will not be set. A temperature reading of −128°C indicates that D+ is shorted to either ground or D-. If the value in the Remote Low Setpoint High Byte (RLSHB) Register is more than −128°C and the ALERT Mask is Disabled, ALERT will be pulled low.

COMMUNICATING WITH THE LM64

Each data register in the LM64 falls into one of four types of user accessibility:

1. Read Only
2. Write Only
3. Read/Write same address
4. Read/Write different address

A Write to the LM64 is comprised of an address byte and a command byte. A write to any register requires one data byte.

Reading the LM64 Registers can take place after the requisite register setup sequence takes place. See LM64 Required Initial Fan Control Register Sequence.

The data byte has the Most Significant Bit (MSB) first. At the end of a read, the LM64 can accept either Acknowledge or No-Acknowledge from the Master. Note that the No-Acknowledge is typically used as a signal for the slave indicating that the Master has read its last byte.

DIGITAL FILTER

The LM64 incorporates a user-configured digital filter to suppress erroneous Remote Temperature readings due to noise. The filter is accessed in the Remote Diode Temperature Filter and Comparator Mode Register. The filter can be set according to the following table.

Level 2 is maximum filtering.

Table 4. Digital Filter Selection Table

D2	D1	Filter
0	0	No Filter
0	1	Level 1
1	0	Level 1
1	1	Level 2

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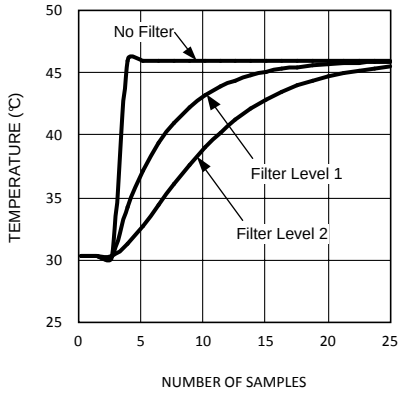


Figure 8. Step Response of the Digital Filter

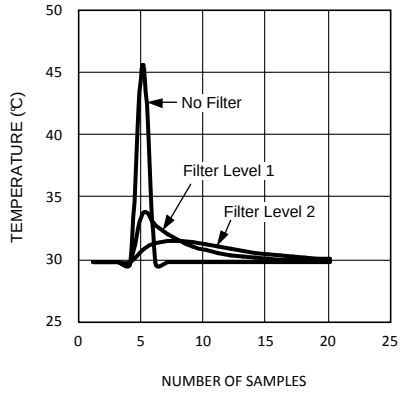
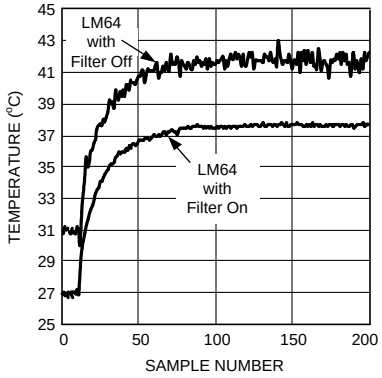


Figure 9. Impulse Response of the Digital Filter



The Filter on and off curves were purposely offset to better show noise performance.

Figure 10. Digital Filter Response in an Intel Pentium 4 processor System

FAULT QUEUE

The LM64 incorporates a Fault Queue to suppress erroneous ALERT triggering . The Fault Queue prevents false triggering by requiring three consecutive out-of-limit HIGH, LOW, or T_CRIT temperature readings. See Figure 11. The Fault Queue defaults to OFF upon power-up and may be activated by setting the RDTS Fault Queue bit in the Configuration Register to a 1.

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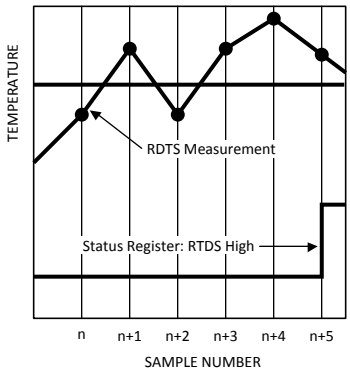

Figure 11. Fault Queue Temperature Response Diagram

ONE-SHOT REGISTER

The One-Shot Register is used to initiate a single conversion and comparison cycle when the device is in standby mode, after which the data returns to standby. This is not a data register. A write operation causes the one-shot conversion. The data written to this address is irrelevant and is not stored. A zero will always be read from this register.

SERIAL INTERFACE RESET

In the event that the SMBus Master is reset while the LM64 is transmitting on the SMBDAT line, the LM64 must be returned to a known state in the communication protocol. This may be done in one of two ways:

1. When SMBDAT is Low, the LM64 SMBus state machine resets to the SMBus idle state if either SMBData or SMBCLK are held Low for more than 35 ms ($t_{TIMEOUT}$). All devices are to timeout when either the SMBCLK or SMBDAT lines are held Low for 25 ms – 35 ms. Therefore, to insure a timeout of all devices on the bus, either the SMBCLK or the SMBData line must be held Low for at least 35 ms.
2. With both SMBDAT and SMBCLK High, the master can initiate an SMBus start condition with a High to Low transition on the SMBDAT line. The LM64 will respond properly to an SMBus start condition at any point during the communication. After the start the LM64 will expect an SMBus Address address byte.

LM64 Registers

The following pages include: LM64 REGISTER MAP IN HEXADECIMAL ORDER a Register Map in Hexadecimal Order, which shows a summary of all registers and their bit assignments, LM64 REGISTER MAP IN FUNCTIONAL ORDER, a Register Map in Functional Order, and LM64 INITIAL REGISTER SEQUENCE AND REGISTER DESCRIPTIONS IN FUNCTIONAL ORDER, a detailed explanation of each register. Do not address the unused or manufacturer's test registers.

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LM64 REGISTER MAP IN HEXADECIMAL ORDER

The following is a Register Map grouped in hexadecimal address order. Some address locations have been left blank to maintain compatibility with LM86. Addresses in parenthesis are mirrors of “Same As” address for backwards compatibility with some older software. Reading or writing either address will access the same 8-bit register.

Register 0x[HEX]	Register Name	DATA BITS							
		D7	D6	D5	D4	D3	D2	D1	D0
00	Local Temperature	LT7	LT6	LT5	LT4	LT3	LT2	LT1	LT0
01	Rmt Temp MSB	RTHB±	RTHB14	RTHB13	RTHB12	RTHB11	RTHB10	RTHB9	RTHB8
02	ALERT Status	BUSY	LHIGH	0	RHIGH	RLOW	RDFA	RCRIT	TACH
03	Configuration	ALTMSK	STBY	PWMDIS	0	0	ALT/TCH	TCRITOV	FLTQUE
04	Conversion Rate	0	0	0	0	CONV3	CONV2	CONV1	CONV0
05	Local High Setpoint	LHS7	LHS6	LHS5	LHS4	LHS3	LHS2	LHS1	LHS0
06	[Reserved]	**Not Used**							
07	Rmt High Setpoint MSB	RHSHB15	RHSHB14	RHHBS13	RHSHB12	RHSHB11	RHSHB10	RHSHB9	RHSHB8
08	Rmt Low Setpoint MSB	RLSHB15	RLSHB14	RLSHB13	RLSHB12	RLHBS11	RLSHB10	RLSHB9	RLSHB8
(09)	Same as 03								
(0A)	Same as 04								
(0B)	Same as 05								
0C	[Reserved]	**Not Used**							
(0D)	Same as 07								
(0E)	Same as 08								
0F	One Shot	**Write Only. Write command triggers one temperature conversion cycle.**							
10	Rmt Temp LSB	RTLB7	RTLB6	RTLB5	0	0	0	0	0
11	Rmt Temp Offset MSB	RTOHB15	RTOHB14	RTOHB13	RTOHB12	RTOHB11	RTOHB10	RTOHB9	RTOHB8
12	Rmt Temp Offset LSB	RTOLB7	RTOLB6	RTOLB5	0	0	0	0	0
13	Rmt High Setpoint LSB	RHSLB7	RHSLB6	RHSLB5	0	0	0	0	0
14	Rmt Low Setpoint LSB	RLSLB7	RLSLB6	RLSLB5	0	0	0	0	0
15	[Reserved]	**Not Used**							
16	ALERT Mask	1	ALTMSK6	1	ALTMSK4	ALTMSK3	1	ALTMSK1	ALTMSK0
17	[Reserved]	**Not Used**							
18	[Reserved]	**Not Used**							
19	Rmt TCRIT Setpoint	RCS7	RCS6	RCS5	RCS4	RCS3	RCS2	RCS1	RCS0
1A	General Purpose Input	0	0	0	GPI5	GPI4	GPI3	GPI2	GPI1

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Register 0x[HEX]	Register Name	DATA BITS							
		D7	D6	D5	D4	D3	D2	D1	D0
1B	General Purpose Output	0	0	0	GPO5	GPO4	GPO3	GPO2	GPO1
1C–1F	[Reserved]	**Not Used**							
20	[Reserved]	**Not Used**							
21	Rmt TCRIT Hysteresis	RTH7	RTH6	RTH5	RTH4	RTH3	RTH2	RTH1	RTH0
22–2F	[Reserved]	**Not Used**							
30–3F	[Reserved]	**Not Used**							
40–45	[Reserved]	**Not Used**							
46	Tach Count LSB	TCLB5	TCLB4	TCLB3	TCLB2	TCLB1	TCLB0	TEDGE1	TEDGE0
47	Tach Count MSB	TCHB13	TCHB12	TCHB11	TCHB10	TCHB9	TCHB8	TCHB7	TCHB6
48	Tach Limit LSB	TLLB7	TLLB6	TLLB5	TLLB4	TLLB3	TLLB2	Not Used	Not Used
49	Tach Limit MSB	TLHB15	TLHB14	TLHB13	TLHB12	TLHB11	TLHB10	TLHB9	TLHB8
4A	PWM and RPM	0	0	PWPGM	PWOUT±	PWCKSL	0	TACH1	TACH0
4B	Fan Spin-Up Config	0	0	SPINUP	SPNDTY1	SPNDTY0	SPNUPT2	SPNUPT1	SPNUPT0
4C	PWM Value	0	0	PWVAL5	PWVAL4	PWVAL3	PWVAL2	PWVAL1	PWVAL0
4D	PWM Frequency	0	0	0	PWMF4	PWMF3	PWMF2	PWMF1	PWMF0
4E	[Reserved]	**Not Used**							
4F	Lookup Table Hystersis	0	0	0	LOOKH4	LOOKH3	LOOKH2	LOOKH1	LOOKH0
50–5F	Lookup Table	**Lookup Table of up to 8 PWM and Temp Pairs in 8-bit Registers**							
60–BE	[Reserved]	**Not Used**							
BF	Rmt Diode Temp Filter	0	0	0	0	0	RDTF1	RDTF0	ALTCOMP
C0–FD	[Reserved]	**Not Used**							
FE	Manufacturer's ID	0	0	0	0	0	0	0	1
FF	Stepping/Die Rev. ID	0	1	0	1	0	0	0	1

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LM64 REGISTER MAP IN FUNCTIONAL ORDER

The following is a Register Map grouped in Functional Order. Some address locations have been left blank to maintain compatibility with LM86. Addresses in parenthesis are mirrors of named address. Reading or writing either address will access the same 8-bit register. The Fan Control and Configuration Registers are listed first, as there is a required order to setup these registers first and then setup the others. The detailed explanations of each register will follow the order shown below. POR = Power-On-Reset.

Register [HEX]	Register Name	Read/Write	POR Default [HEX]
FAN CONTROL REGISTERS			
4A	PWM and RPM	R/W	20
4B	Fan Spin-Up Configuration	R/W	3F
4D	PWM Frequency	R/W	17
4C	PWM Value	Read Only (R/W if Override Bit is Set)	00
50–5F	Lookup Table	R/W	See Table
4F	Lookup Table Hysteresis	R/W	04
CONFIGURATION REGISTER			
03 (09)	Configuration	R/W	00
TACHOMETER COUNT AND LIMIT REGISTERS			
46	Tach Count LSB	Read Only	N/A
47	Tach Count MSB	Read Only	N/A
48	Tach Limit LSB	R/W	FF
49	Tach Limit MSB	R/W	FF
LOCAL TEMPERATURE AND LOCAL SETPOINT REGISTERS			
00	Local Temperature	Read Only	N/A
05 (0B)	Local High Setpoint	R/W	46 (70°)
REMOTE DIODE TEMPERATURE AND SETPOINT REGISTERS			
01	Remote Temperature MSB	Read Only	N/A
10	Remote Temperature LSB	Read Only	N/A
11	Remote Temperature Offset MSB	R/W	00
12	Remote Temperature Offset LSB	R/W	00
07 (0D)	Remote High Setpoint MSB	R/W	46 (70°C)
13	Remote High Setpoint LSB	R/W	00
08 (0E)	Remote Low Setpoint MSB	R/W	00 (0°C)
14	Remote Low Setpoint LSB	R/W	00
19	Remote TCRIT Setpoint	R/W	55 (85°C)
21	Remote TCRIT Hys	R/W	0A (10°C)
BF	Remote Diode Temperature Filter	R/W	00
CONVERSION AND ONE-SHOT REGISTERS			
04 (0A)	Conversion Rate	R/W	08
0F	One-Shot	Write Only	N/A
ALERT STATUS AND MASK REGISTERS			
02	ALERT Status	Read Only	N/A
16	ALERT Mask	R/W	A4
ID REGISTERS			
FE	Manufacturer's ID	Read Only	01
FF	Stepping/Die Rev. ID	Read Only	51
GENERAL PURPOSE REGISTERS			
1A	General Purpose Input	Read Only	See (1)

(1) For Register 0x1A the Power-On-Reset for the five LSB's are the logic states present on the 5 GPIOx pins.

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Register [HEX]	Register Name	Read/Write	POR Default [HEX]
1B	General Purpose Output	R/W	See (2)
[RESERVED] REGISTERS—NOT USED			
06	Not Used	N/A	N/A
0C	Not Used	N/A	N/A
15	Not Used	N/A	N/A
17	Not Used	N/A	N/A
18	Not Used	N/A	N/A
1C–1F	Not Used	N/A	N/A
20	Not Used	N/A	N/A
22–2F	Not Used	N/A	N/A
30–3F	Not Used	N/A	N/A
40–45	Not Used	N/A	N/A
4E	Not Used	N/A	N/A
60–BE	Not Used	N/A	N/A
C0–FD	Not Used	N/A	N/A

(2) For Register 0x1B the Power-On-Reset for the five LSB's are the logic states present on the 5 GPDx pins.

LM64 INITIAL REGISTER SEQUENCE AND REGISTER DESCRIPTIONS IN FUNCTIONAL ORDER

The following is a Register Map grouped in functional and sequence order. Some address locations have been left blank to maintain compatibility with LM86. Addresses in parenthesis are mirrors of named address for backwards compatibility with some older software. Reading or writing either address will access the same 8-bit register.

LM64 Required Initial Fan Control Register Sequence

Important! The BIOS must follow the sequence below to configure the following Fan Registers for the LM64 before using any of the Fan or Tachometer or PWM registers:

Step	$[Register]_{HEX}$ and Setup Instructions(1)
1	[4A] Write bits 0 and 1; 3 and 4. This includes tach settings if used, PWM internal clock select (1.4 kHz or 360 kHz) and PWM Output Polarity.
2	[4B] Write bits 0 through 5 to program the spin-up settings.
3	[4D] Write bits 0 through 4 to set the frequency settings. This works with the PWM internal clock select.
4	Choose, then write, **only one** of the following: A. [4F–5F] the Lookup Table, **or** B. [4C] the PWM value bits 0 through 5.
5	If Step 4A, Lookup Table, was chosen and written then write [4A] bit 5 = 0.

(1) All other registers can be written at any time after the above sequence.

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LM64 REGISTER DESCRIPTIONS IN FUNCTIONAL ORDER

Fan Control Registers

Address Hex	Read/ Write	Bits	POR Value	Name	Description
$4A_{HEX}$ PWM AND RPM REGISTER					
4A	R/W	7:6	00	PWM Program	These bits are unused and always set to 0.
		5	1		0: the PWM Value (register 4C) and the Lookup Table (50–5F) are read-only. The PWM value (0 to 100%) is determined by the current remote diode temperature and the Lookup Table, and can be read from the PWM value register. 1: the PWM value (register 4C) and the Lookup Table (Register 50–5F) are read/write enabled. Writing the PWM Value register will set the PWM output. This is also the state during which the Lookup Table can be written.
		4	0	PWM Output Polarity	0: the PWM output pin will be 0 V for fan OFF and open for fan ON. 1: the PWM output pin will be open for fan OFF and 0 V for fan ON.
		3	0	PWM Clock Select	if 0, the master PWM clock is 360 kHz if 1, the master PWM clock is 1.4 kHz.
		2	0	[Reserved]	Always write 0 to this bit.
		1:0	00	Tachometer Mode	00: Traditional tach input monitor, false readings when under minimum detectable RPM. 01: Traditional tach input monitor, FFFF reading when under minimum detectable RPM. 10: Most accurate readings, FFFF reading when under minimum detectable RPM. 11: Least effort on programmed PWM of fan, FFFF reading when under minimum detectable RPM. Note: If the PWM Clock is 360 kHz, mode 00 is used regardless of the setting of these two bits.
$4B_{HEX}$ FAN SPIN-UP CONFIGURATION REGISTER					
4B	R/W	7:6	0	Fast Tachometer Spin-Up	These bits are unused and always set to 0
		5	1		If 0, the fan spin-up uses the duty cycle and spin-up time, bits 0–4. If 1, the LM64 sets the PWM output to 100% until the spin-up times out (per bits 0–2) or the minimum desired RPM has been reached (per the Tachometer Setpoint setting) using the tachometer input, whichever happens first. This bit overrides the PWM Spin-Up Duty Cycle register (bits 4:3)—PWM output is always 100%. If PWM Spin-Up Time (bits 2:0) = 000, the Spin-Up cycle is bypassed, regardless of the state of this bit.
		4:3	11	PWM Spin-Up Duty Cycle	00: Spin-Up cycle bypassed (no Spin-Up), unless Fast Tachometer Terminated Spin-Up (bit 5) is set. 01: 50% 10: 75%–81% Depends on PWM Frequency. See Applications Notes. 11: 100%
		2:0	111	PWM Spin-Up Time	000: Spin-Up cycle bypassed (No Spin-Up) 001: 0.05 seconds 010: 0.1 s 011: 0.2 s 100: 0.4 s 101: 0.8 s 110: 1.6 s 111: 3.2 s
$4D_{HEX}$ FAN PWM FREQUENCY REGISTER					
4D	R/W	7:5	000	PWM Frequency	These bits are unused and always set to 0
		4:0	10111		The PWM Frequency = PWM_Clock / 2n, where PWM_Clock = 360 kHz or 1.4 kHz (per the PWM Clock Select bit in Register 4A), and n = value of the register. Note: n = 0 is mapped to n = 1. See the Applications Notes at the end of this datasheet.

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Address Hex	Read/ Write	Bits	POR Value	Name	Description
$4C_{HEX}$ PWM VALUE REGISTER					
4C	Read (Write only if reg 4A bit 5 = 1.)	7:6	00	PWM Value	These bits are unused and always set to 0
		5:0	000000		If PWM Program (register 4A, bit 5) = 0 this register is read only and reflects the LM64's current PWM value from the Lookup Table. If PWM Program (register 4A, bit 5) = 1, this register is read/write and the desired PWM value is written directly to this register, instead of from the Lookup Table, for direct fan speed control. This register will read 0 during the Spin-Up cycle. See Application Notes section at the end of this datasheet for more information regarding the PWM Value and Duty Cycle in %.
50_{HEX} to $5F_{HEX}$ LOOKUP TABLE (7 Bits for Temperature and 6 Bits for PWM for each Temperature/PWM Pair)					
50	Read. (Write only if reg 4A bit 5 = 1.)	7	0	Lookup Table Temperature Entry 1	This bit is unused and always set to 0.
		6:0	0x7F		If the remote diode temperature exceeds this value, the PWM output will be the value in Register 51.
51		7:6	00	Lookup Table PWM Entry 1	These bits are unused and always set to 0.
		5:0	0x3F		The PWM value corresponding to the temperature limit in register 50.
52		7	0	Lookup Table Temperature Entry 2	This bit is unused and always set to 0.
		6:0	0x7F		If the remote diode temperature exceeds this value, the PWM output will be the value in Register 53.
53		7:6	00	Lookup Table PWM Entry 2	These bits are unused and always set to 0.
		5:0	0x3F		The PWM value corresponding to the temperature limit in register 52.
54		7	0	Lookup Table Temperature Entry 3	This bit is unused and always set to 0.
		6:0	0x7F		If the remote diode temperature exceeds this value, the PWM output will be the value in Register 55.
55		7:6	00	Lookup Table PWM Entry 3	These bits are unused and always set to 0.
		5:0	0x3F		The PWM value corresponding to the temperature limit in register 54.
56		7	0	Lookup Table Temperature Entry 4	This bit is unused and always set to 0.
		6:0	0x7F		If the remote diode temperature exceeds this value, the PWM output will be the value in Register 57.
57		7:6	00	Lookup Table PWM Entry 4	These bits are unused and always set to 0.
		5:0	0x3F		The PWM value corresponding to the temperature limit in register 56.
58		7	0	Lookup Table Temperature Entry 5	This bit is unused and always set to 0.
		6:0	0x7F		If the remote diode temperature exceeds this value, the PWM output will be the value in Register 59.
59		7:6	00	Lookup Table PWM Entry 5	These bits are unused and always set to 0.
		5:0	0x3F		The PWM value corresponding to the temperature limit in register 58.
5A		7	0	Lookup Table Temperature Entry 6	This bit is unused and always set to 0.
		6:0	0x7F		If the remote diode temperature exceeds this value, the PWM output will be the value in Register 5B.
5B		7:6	00	Lookup Table PWM Entry 6	These bits are unused and always set to 0.
		5:0	0x3F		The PWM value corresponding to the temperature limit in register 5A.
5C		7	0	Lookup Table Temperature Entry 7	This bit is unused and always set to 0.
		6:0	0x7F		If the remote diode temperature exceeds this value, the PWM output will be the value in Register 5D.
5D		7:6	00	Lookup Table PWM Entry 7	These bits are unused and always set to 0.
		5:0	0x3F		The PWM value corresponding to the temperature limit in register 5C.
5E		7	0	Lookup Table Temperature Entry 8	This bit is unused and always set to 0.
		6:0	0x7F		If the remote diode temperature exceeds this value, the PWM output will be the value in Register 5F.
5F		7:6	00	Lookup Table PWM Entry 8	These bits are unused and always set to 0.
		5:0	0x3F		The PWM value corresponding to the temperature limit in register 5E.

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Address Hex	Read/ Write	Bits	POR Value	Name	Description
4F$_{HEX}$ LOOKUP TABLE HYSTERESIS					
4F	R/W	7:5	000	Lookup Table Hysteresis	These bits are unused and always set to 0
		4:0	00100		The amount of hysteresis applied to the Lookup Table. (1 LSB = 1°C).

Configuration Register

ADDRESS Hex	Read/ Write	Bits	POR Value	Name	Description
03 (09)$_{HEX}$ CONFIGURATION REGISTER					
03 (09)	R/W	7	0	ALERT Mask	When this bit is a 0, ALERT interrupts are enabled. When this bit is set to a 1, ALERT interrupts are masked, and the $\overline{\text{ALERT}}$ pin is always in a high impedance (open) state.
		6	0	STANDBY	When this bit is a 0, the LM64 is in operational mode, converting, comparing, and updating the PWM output continuously. When this bit is a 1, the LM64 enters a low power standby mode. In STANDBY, continuous conversions are stopped, but a conversion/comparison cycle may be initiated by writing any value to register 0x0F. Operation of the PWM output in STANDBY depends on the setting of bit 5 in this register.
		5	0	PWM Disable in STANDBY	When this bit is a 0, the LM64's PWM output continues to output the current fan control signal while in STANDBY. When this bit is a 1, the PWM output is disabled (as defined by the PWM polarity bit) while in STANDBY.
		4:1	0000		These bits are unused and always set to 0.
		0	0	RDTS Fault Queue	0: an ALERT will be generated if any Remote Diode conversion result is above the **Remote High Set Point or below the Remote Low Setpoint**. 1: an ALERT will be generated only if three consecutive Remote Diode conversions are above the **Remote High Set Point or below the Remote Low Setpoint**.

Tachometer Count And Limit Registers

ADDRESS Hex	Read/ Write	Bits	POR Value	Name	Description
47$_{HEX}$ TACHOMETER COUNT (MSB) and 46$_{HEX}$ TACHOMETER COUNT (LSB) REGISTERS (16 bits: Read LSB first to lock MSB and ensure MSB and LSB are from the same reading)					
47	Read Only	7:0	N/A	Tachometer Count (MSB)	These registers contain the current 16-bit Tachometer Count, representing the period of time between tach pulses. Note that the 16-bit tachometer MSB and LSB are reversed from the 16-bit temperature readings
46	Read Only	7:2	N/A	Tachometer Count (MSB)	
	Read Only	1:0	00	Tachometer Edge Count	**Bits:** / **Edges Used** / **Tach_Count_Multiple** 00: Reserved - do not use 01: 2 / 4 10: 2 / 2 11: 5 / 1 Note: If PWM_Clock_Select = 360 kHz, then Tach_Count_Multiple = 1 regardless of the setting of these bits.
49$_{HEX}$ TACHOMETER LIMIT (MSB) and 48$_{HEX}$ TACHOMETER LIMIT (LSB) REGISTERS					
49	R/W	7:0	0xFF	Tachometer Limit (MSB)	These registers contain the current 16-bit Tachometer Count, representing the period of time between tach pulses. Fan RPM = (f * 5,400,000) / (Tachometer Count), where f = 1 for 2 pulses/rev fan; f = 2 for 1 pulse/rev fan; and f = 2/3 for 3 pulses/rev fan. See the Application Notes section for more tachometer information. Note that the 16-bit tachometer MSB and LSB are reversed from the 16 bit temperature readings.
48	R/W	7:2	0xFF	Tachometer Limit (LSB)	
	R/W	1:0		[Reserved]	Not Used.

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Local Temperature And Local High Setpoint Registers

ADDRESS Hex	Read/ Write	Bits	POR Value	Name	Description
00_{HEX} LOCAL TEMPERATURE REGISTER (8-bits)					
00	Read Only	7:0	N/A	Local Temperature Reading (8-bit)	8-bit temperature of the LM64.
05 $(0B)_{HEX}$ LOCAL HIGH SETPOINT REGISTER (8-bits)					
05	R/W	7:0	0x46 (70°)	Local HIGH Setpoint	High Setpoint for the internal diode.

Remote Diode Temperature, Offset And Setpoint Registers

ADDRESS Hex	Read/ Write	Bits	POR Value	Name	Description
01	Read Only	7:0	N/A	Remote Diode Temperature Reading (MSB)	This is the MSB of the LM64 remote diode temperature value, 2's complement. Bit 7 is the sign bit, bit 6 has a weight 64°C, and bit 0 has a weight of 1°C. **Read this byte first.** The actual remote diode temperature is 16°C higher than the values in registers 0x01 and 0x10.
10	Read Only	7:5	N/A	Remote Diode Temperature Reading (LSB)	This is the LSB of the LM64 remote diode temperature value, in 2's complement. Bit 7 has a weight 0.5°C, bit 6 has a weight of 0.25°C, and bit 5 has a weight of 0.125°C. The actual remote diode temperature is 16°C higher than the values in registers 0x01 and 0x10.
		4:0	00		Always 00.
11	R/W	7:5	00	Remote Temperature OFFSET (MSB)	These registers contain the offset value added to, or subtracted from, the remote diode's reading to compensate for the different non-ideality factors of different processors, diodes, etc. The 2's complement value, in these registers is added to the output of the LM64's ADC to form the temperature reading contained in registers 01 and 10.
12	R/W	7:5	00	Remote Temperature OFFSET (LSB)	
		4:0	00		Always 00.
07 (0D)	R/W	7:0	0x46 (70°C)	Remote HIGH Setpoint (MSB)	High setpoint temperature for remote diode. Same format as **Remote Temperature Reading** (registers 01 and 10).
13	R/W	7:5	00	Remote HIGH Setpoint (LSB)	
		4:0	00		Always 00.
08 (0E)	R/W	7:0	00 (0°C)	Remote LOW Setpoint (MSB)	Low setpoint temperature for remote diode. Same format as **Remote Temperature Reading** (registers 01 and 10).
14	R/W	7:5	00	Remote LOW Setpoint (LSB)	
		4:0	00		Always 00.
19	R/W	7:0	0x55 (85°C)	Remote Diode T_CRIT Limit	This 8-bit integer storing the T_CRIT limit is initially 85°C (101°C actual remote T_Crit limit). This value can be changed at any time after power-up.
21	R/W	7:0	0x0A (10°C)	Remote Diode T_CRIT Hysteresis	8-bit integer storing T_CRIT hysteresis. T_CRIT stays activated until the remote diode temperature goes below [(T_CRIT Limit)—(T_CRIT Hysteresis)].
BF	R/W	7:3	00000		These bits are unused and should always set to 0.
		2:1	00	Remote Diode Temperature Filter	00: Filter Disabled 01: Filter Level 1 (minimal filtering, same as 10) 10: Filter Level 1 (minimal filtering, same as 01) 11: Filter Level 2 (maximum filtering)
		0	0	Comparator Mode	0: the $\overline{\text{ALERT}}$ pin functions as an Interrupt or ARA mode. 1: the $\overline{\text{ALERT}}$ pin behaves as a comparator, asserting itself when an ALERT condition exists, de-asserting itself when the ALERT condition goes away.

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ALERT Status And Mask Registers

ADDRESS Hex	Read/ Write	Bits	POR Value	Name	Description
02_{HEX} ALERT STATUS REGISTER (8-bits) (All Alarms are latched until read, then cleared if alarm condition was removed at the time of the read.)					
0x02	Read Only	7	0	Busy	When this bit is a 0, the ADC is not converting. When this bit is set to a 1, the ADC is performing a conversion. This bit does not affect ALERT status.
		6	0	Local High Alarm	When this bit is a 0, the internal temperature of the LM64 is at or below the Local High Setpoint. When this bit is a 1, the internal temperature of the LM64 is above the Local High Setpoint, and an ALERT is triggered.
		5	0		This bit is unused and always read as 0.
		4	0	Remote High Alarm	When this bit is a 0, the temperature of the Remote Diode is at or below the Remote High Setpoint. When this bit is a 1, the temperature of the Remote Diode is above the Remote High Setpoint, and an ALERT is triggered.
		3	0	Remote Low Alarm	When this bit is a 0, the temperature of the Remote Diode is at or above the Remote Low Setpoint. When this bit is a 1, the temperature of the Remote Diode is below the Remote Low Setpoint, and an ALERT is triggered.
		2	0	Remote Diode Fault Alarm	When this bit is a 0, the Remote Diode appears to be correctly connected. When this bit is a 1, the Remote Diode may be disconnected or shorted. This Alarm does not trigger an ALERT.
		1	0	Remote T_CRIT Alarm	When this bit is a 0, the temperature of the Remote Diode is at or below the T_CRIT Limit. When this bit is a 1, the temperature of the Remote Diode is above the T_CRIT Limit, and an ALERT is triggered.
		0	0	Tach Alarm	When this bit is a 0, the Tachometer count is lower than or equal to the Tachometer Limit (the RPM of the fan is greater than or equal to the minimum desired RPM). When this bit is a 1, the Tachometer count is higher than the Tachometer Limit (the RPM of the fan is less than the minimum desired RPM), and an ALERT is triggered.
16_{HEX} ALERT MASK REGISTER (8-bits)					
16	R/W	7	1		This bit is unused and always read as 1.
		6	0	Local High Alarm Mask	When this bit is a 0, a Local High Alarm event will generate an ALERT. When this bit is a 1, a Local High Alarm will not generate an ALERT
		5	1		This bit is unused and always read as 1.
		4	0	Remote High Alarm Mask	When this bit is a 0, Remote High Alarm event will generate an ALERT. When this bit is a 1, a Remote High Alarm event will not generate an ALERT.
		3	0	Remote Low Alarm Mask	When this bit is a 0, a Remote Low Alarm event will generate an ALERT. When this bit is a 1, a Remote Low Alarm event will not generate an ALERT.
		2	1		This bit is unused and always read as 1.
		1	0	Remote T_CRIT Alarm Mask	When this bit is a 0, a Remote T_CRIT event will generate an ALERT. When this bit is a 1, a Remote T_CRIT event will not generate an ALERT.
		0	0	Tach Alarm Mask	When this bit is a 0, a Tach Alarm event will generate an ALERT. When this bit is a 1, a Tach Alarm event will not generate an ALERT.

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Conversion Rate And One-Shot Registers

ADDRESS Hex	Read/ Write	Bits	POR Value	Name	Description
04 (0A)$_{HEX}$ CONVERSION RATE REGISTER (8-bits)					
04 (0A)	R/W	7:0	0x08	Conversion Rate	Sets the conversion rate of the LM64. 00000000 = 0.0625 Hz 00000001 = 0.125 Hz 00000010 = 0.25 Hz 00000011 = 0.5 Hz 00000100 = 1 Hz 00000101 = 2 Hz 00000110 = 4 Hz 00000111 = 8 Hz 00001000 = 16 Hz 00001001 = 32 Hz All other values = 32 Hz
04 (0A)$_{HEX}$ ONE-SHOT REGISTER (8-bits)					
0F	Write Only	7:0	N/A	One Shot Trigger	With the LM64 in the STANDBY mode a single write to this register will initiate one complete temperature conversion cycle.

ID Registers

ADDRESS Hex	Read/ Write	Bits	POR Value	Name	Description
FF$_{HEX}$ STEPPING / DIE REVISION ID REGISTER (8-bits)					
FF	Read Only	7:0	0x51	Stepping/Die Revision ID	Version of LM64
FE$_{HEX}$ MANUFACTURER'S ID REGISTER (8-bits)					
FE	Read Only	7:0	0x01	Manufacturer's ID	0x01 = Texas Instruments

General Purpose Registers

ADDRESS Hex	Read/ Write	Bits	POR Value	Name	Description
1A$_{HEX}$ GENERAL PURPOSE INPUT REGISTER (8-bits)					
1A	Read Only	7:5	000		These bits are unused and always set to 0.
		4:0	See (1)	General Purpose Input	These 5 bits reflect the logic states of the GPIOx pins.
1B$_{HEX}$ GENERAL PURPOSE OUTPUT REGISTER (8-bits)					
1B	R/W	7:5	000		These bits are unused and always set to 0.
		4:0	See (2)	General Purpose Output	These 5 bits reflect the GPI register bits [4:0] except for Power-On-Default when they are the 5 logic states of the General Pupose Default (GPD) input pins.

(1) For Register 0x1A the Power-On-Reset for the five LSB's are the logic states present on the 5 GPIOx pins.
(2) For Register 0x1B the Power-On-Reset for the five LSB's are the logic states present on the 5 GPDx pins.

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Application Notes

FAN CONTROL DUTY CYCLE VS. REGISTER SETTINGS AND FREQUENCY

PWM Freq 4D [4:0]	Step Resolution, %	PWM Value 4D [5:0] for 100%	PWM Value 4C [5:0] for about 75%	PWM Value 4C [5:0] for 50%	PWM Freq at 360 kHz Internal Clock, kHz	PWM Freq at 1.4 kHz Internal Clock, Hz	Actual Duty Cycle, % When 75% is Selected
0	Address 0 is mapped to Address 1						
1	50	2	1	1	180.0	703.1	50.0
2	25	4	3	2	90.00	351.6	75.0
3	16.7	6	5	3	60.00	234.4	83.3
4	12.5	8	6	4	45.00	175.8	75.0
5	10.0	10	8	5	36.00	140.6	80.0
6	8.33	12	9	6	30.00	117.2	75.0
7	7.14	14	11	7	25.71	100.4	78.6
8	6.25	16	12	8	22.50	87.9	75.0
9	5.56	18	14	9	20.00	78.1	77.8
10	5.00	20	15	10	18.00	70.3	75.0
11	4.54	22	17	11	16.36	63.9	77.27
12	4.16	24	18	12	15.00	58.6	75.00
13	3.85	26	20	13	13.85	54.1	76.92
14	3.57	28	21	14	12.86	50.2	75.00
15	3.33	30	23	15	12.00	46.9	76.67
16	3.13	32	24	16	11.25	43.9	75.00
17	2.94	34	26	17	10.59	41.4	76.47
18	2.78	36	27	18	10.00	39.1	75.00
19	2.63	38	29	19	9.47	37.0	76.32
20	2.50	40	30	20	9.00	35.2	75.00
21	2.38	42	32	21	8.57	33.5	76.19
22	2.27	44	33	22	8.18	32.0	75.00
23	2.17	46	35	23	7.82	30.6	76.09
24	2.08	48	36	24	7.50	29.3	75.00
25	2.00	50	38	25	7.20	28.1	76.00
26	1.92	52	39	26	6.92	27.0	75.00
27	1.85	54	41	27	6.67	26.0	75.93
28	1.79	56	42	28	6.42	25.1	75.00
29	1.72	58	44	29	6.21	24.2	75.86
30	1.67	60	45	30	6.00	23.4	75.00
31	1.61	62	47	31	5.81	22.7	75.81

Computing Duty Cycles for a Given Frequency

Select a PWM Frequency from the first column corresponding to the desired actual frequency in columns 6 or 7. Note the PWM Value for 100% Duty Cycle.

Find the Duty Cycle by taking the PWM Value of Register 4C and computing:

$$DutyCycle\ _(\%) = \frac{PWM\ _Value}{PWM\ _Value\ _\ for\ _100\%} \times 100\% \quad (1)$$

Example: For a PWM Frequency of 24, a PWM Value at 100% = 48 and PWM Value actual = 28, then the Duty Cycle is (28/48) × 100% = **58.3%**.

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USE OF THE LOOKUP TABLE FOR NON-LINEAR PWM VALUES VS TEMPERATURE

The Lookup Table, Registers 50 through 5F, can be used to create a non-linear PWM vs Temperature curve that could be used to reduce the acoustic noise from processor fan due to linear or step transfer functions. An example is given below:

EXAMPLE:

In a particular system it was found that the best acoustic fan noise performance was found to occur when the PWM vs Temperature transfer function curve was parabolic in shape.

From 25°C to 105°C the fan is to go from 20% to 100%. Since there are 8 steps to the Lookup Table we will break up the Temperature range into 8 separate temperatures. For the 80°C over 8-steps = 10°C per step. This takes care of the x-axis.

For the PWM Value, we first select the PWM Frequency. In this example we will make the PWM Frequency (Register 4C) 20.

For 100% Duty Cycle then, the PWM value is 40. For 20% the minimum is 40 x (0.2) = 8.

We can then arrange the PWM, Temperature pairs in a parabolic fashion in the form of $y = 0.005 \bullet (x - 25)^2 + 8$

Temperature	PWM Value Calculated	Closest PWM Value
25	8.0	8
35	8.5	9
45	10.0	10
55	12.5	13
65	16.0	16
75	20.5	21
85	26.0	26
95	32.5	33
105	40.0	40

We can then program the Lookup Table with the temperature and Closest PWM Values required for the curve required in our example.

NON-IDEALITY FACTOR AND TEMPERATURE ACCURACY

The LM64 can be applied to remote diode sensing in the same way as other integrated-circuit temperature sensors. It can be soldered to a printed-circuit board, and because the path of best thermal conductivity is between the die and the pins, its temperature will effectively be that of the printed-circuit board lands and traces soldered to its pins. This presumes that the ambient air temperature is nearly the same as the surface temperature of the printed-circuit board. If the air temperature is much higher or lower than the surface temperature, the actual temperature of the LM64 die will be an intermediate temperature between the surface and air temperatures. Again, the primary thermal conduction path is through the leads, so the circuit board surface temperature will contribute to the die temperature much more than the air temperature.

To measure the temperature external to the die use a remote diode. This diode can be located on the die of the target IC, such as a CPU processor chip, allowing measurement of the IC's temperature, independent of the LM64's temperature. The LM64 has been optimized for use with a MMBT3904 diode-connected transistor.

A discrete diode can also be used to sense the temperature of external objects or ambient air. Remember that a discrete diode's temperature will be affected, and often dominated by, the temperature of its leads.

Most silicon diodes do not lend themselves well to this application. It is recommended that a diode-connected MMBT3904 transistor be used. The base of the transistor is connected to the collector and becomes the anode. The emitter is the cathode.

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Diode Non_Ideality

When a transistor is connected to a diode the following relationship holds for V_{be}, T, and I_F:

$$I_F = I_S \cdot \left[e^{\left(\frac{V_{be}}{\eta \cdot V_T} \right)} - 1 \right] \tag{2}$$

where

$$V_T = \frac{kT}{q}$$

- q = 1.6x10^{-19} Coulombs (the electron charge)
- T = Absolute Temperature in Kelvin
- k = 1.38x10^{-23} joules/K (Boltzmann's constant)
- η is the non-ideality factor of the manufacturing process used to make the thermal diode
- I_s = Saturation Current and is process dependent
- I_f = Forward Current through the base emitter junction
- V_{be} = Base Emitter Voltage Drop (3)

In the active region, the −1 term is negligible and may be eliminated, yielding the following equation

$$I_F = I_S \cdot \left[e^{\left(\frac{V_{be}}{\eta \cdot V_T} \right)} \right] \tag{4}$$

In the above equation, η and I_s are dependent upon the process that was used in the fabrication of the particular diode. By forcing two currents with a very controlled ratio (N) and measuring the resulting voltage difference, it is possible to eliminate the I_s term. Solving for the forward voltage difference yields the relationship:

$$\Delta V_{be} = \eta \left(\frac{kT}{q} \right) \cdot \ln (N) \tag{5}$$

The non-ideality factor, η, is the only other parameter not accounted for and depends on the diode that is used for measurement. Since ΔV_{be} is proportional to both η and T, the variations in η cannot be distinguished from variations in temperature. Since the temperature sensor does not control the non-ideality factor, it will directly add to the inaccuracy of the sensor.

For example, if a processor manufacturer specifies a ±0.1% variation in η from part to part. As an example, assume that a temperature sensor has an accuracy specification of ±1°C at room temperature of 25°C. The resulting accuracy will be:

T_{ACC} = ±1°C + (±0.1% of 298°K) = ±1.3°C

The additional inaccuracy in the temperature measurement caused by η, can be eliminated if each temperature sensor is calibrated with the remote diode that it will be paired with. Refer to the processor datasheet for the non-ideality factor.

Compensating for Diode Non-Ideality

In order to compensate for the errors introduced by non-ideality, the temperature sensor is calibrated for a particular processor. Texas Instruments temperature sensors are always calibrated to the typical non-ideality of a particular processor type.

The LM64 is calibrated for a MMBT3904 diode-connected transistor.

When a temperature sensor, calibrated for a specific type of processor is used with a different processor type or a given processor type has a non-ideality that strays form the typical value, errors are introduced.

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Temperature errors associated with non-ideality may be introduced in a specific temperature range of concern through the use of the Temperature Offset Registers 11_{HEX} and 12_{HEX}.

The user is encouraged to send an e-mail to **hardware.monitor.team@nsc.com** to further request information on our recommended setting of the offset register for different processor types.

COMPUTING RPM OF THE FAN FROM THE TACH COUNT

The Tach Count Registers 46_{HEX} and 47_{HEX} count the number of periods of the 90 kHz tachometer clock in the LM64 for the tachometer input from the fan assuming a 2 pulse per revolution fan tachometer, such as the fans supplied with the Pentium 4 boxed processors. The RPM of the fan can be computed from the Tach Count Registers 46_{HEX} and 47_{HEX}. This can best be shown through an example.

Example:

Given: the fan used has a tachometer output with 2 per revolution.

Let:

Register 46 (LSB) is BF_{HEX} = Decimal (11 x 16) + 15 = 191 and

Register 47 (MSB) is 7_{HEX} = Decimal (7 x 256) = 1792.

The total Tach Count, in decimal, is 191 + 1792 = **1983**.

The RPM is computed using the formula

$$Fan_RPM = \frac{f \times 5,400,000}{Total_Tach_Count_(Decimal)}, \quad (6)$$

where

f = 1 for 2 pulses/rev fan tachometer output;

f = 2 for 1 pulse/rev fan tachometer output, and

f = 2 / 3 for 3 pulses/rev fan tachometer output

For our example

$$Fan_RPM = \frac{1 \times 5,400,000}{1983} = 2723_RPM \quad (7)$$

PCB LAYOUT FOR MINIMIZING NOISE

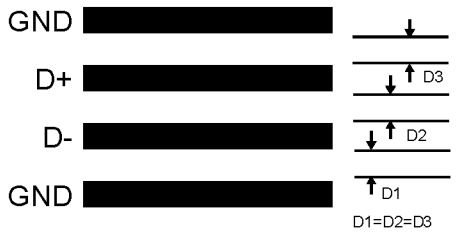

Figure 12. Ideal Diode Trace Layout

In a noisy environment, such as a processor mother board, layout considerations are very critical. Noise induced on traces running between the remote temperature diode sensor and the LM64 can cause temperature conversion errors. Keep in mind that the signal level the LM64 is trying to measure is in microvolts. The following guidelines should be followed:

1. Place a 0.1 µF power supply bypass capacitor as close as possible to the V_{DD} pin and the recommended 2.2 nF capacitor as close as possible to the LM64's D+ and D− pins. Make sure the traces to the 2.2 nF capacitor are matched.
2. Ideally, the LM64 should be placed within 10 cm of the Processor diode pins with the traces being as straight, short and identical as possible. Trace resistance of 1 Ω can cause as much as 1°C of error. This

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error can be compensated by using the Remote Temperature Offset Registers, since the value placed in these registers will automatically be subtracted from or added to the remote temperature reading.

3. Diode traces should be surrounded by a GND guard ring to either side, above and below if possible. This GND guard should not be between the D+ and D− lines. In the event that noise does couple to the diode lines it would be ideal if it is coupled common mode. That is equally to the D+ and D− lines.
4. Avoid routing diode traces in close proximity to power supply switching or filtering inductors.
5. Avoid running diode traces close to or parallel to high speed digital and bus lines. Diode traces should be kept at least 2 cm apart from the high speed digital traces.
6. If it is necessary to cross high speed digital traces, the diode traces and the high speed digital traces should cross at a 90 degree angle.
7. The ideal place to connect the LM64's GND pin is as close as possible to the Processor's GND associated with the sense diode.
8. Leakage current between D+ and GND should be kept to a minimum. One nano-ampere of leakage can cause as much as 1°C of error in the diode temperature reading. Keeping the printed circuit board as clean as possible will minimize leakage current.

Noise coupling into the digital lines greater than 400 mVp-p (typical hysteresis) and undershoot less than 500 mV below GND, may prevent successful SMBus communication with the LM64. SMBus no acknowledge is the most common symptom, causing unnecessary traffic on the bus. Although the SMBus maximum frequency of communication is rather low (100 kHz max), care still needs to be taken to ensure proper termination within a system with multiple parts on the bus and long printed circuit board traces. An RC lowpass filter with a 3 dB corner frequency of about 40 MHz is included on the LM64's SMBCLK input. Additional resistance can be added in series with the SMBData and SMBCLK lines to further help filter noise and ringing. Minimize noise coupling by keeping digital traces out of switching power supply areas as well as ensuring that digital lines containing high speed data communications cross at right angles to the SMBData and SMBCLK lines.

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REVISION HISTORY

Changes from Original (March 2013) to Revision A	Page
• Changed layout of National Data Sheet to TI format	32

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM64CILQ-F/NOPB	ACTIVE	WQFN	NHW	24	1000	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	0 to 125	64CILQF	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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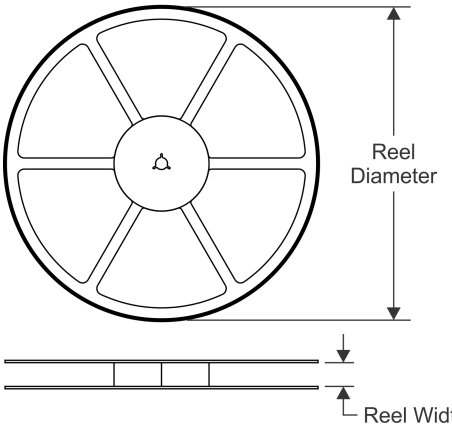
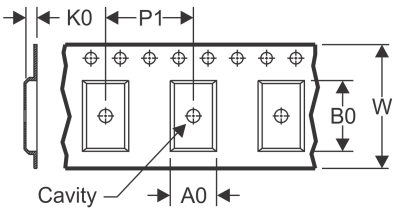
TAPE AND REEL INFORMATION

REEL DIMENSIONS

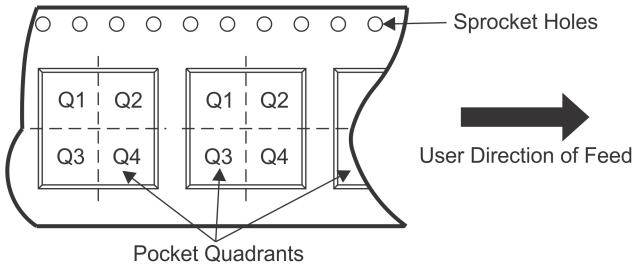


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

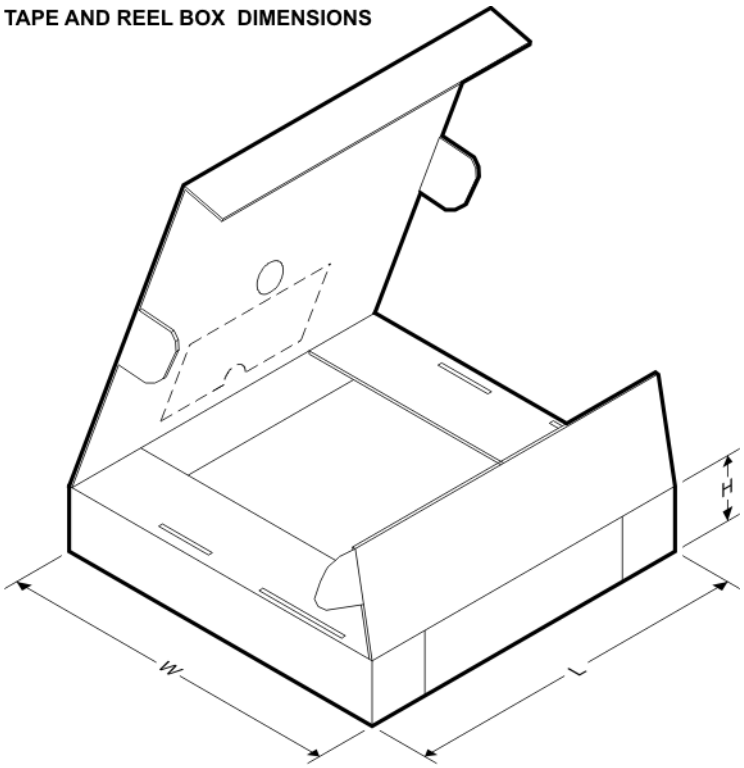
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM64CILQ-F/NOPB	WQFN	NHW	24	1000	178.0	12.4	4.3	5.3	1.3	8.0	12.0	Q1

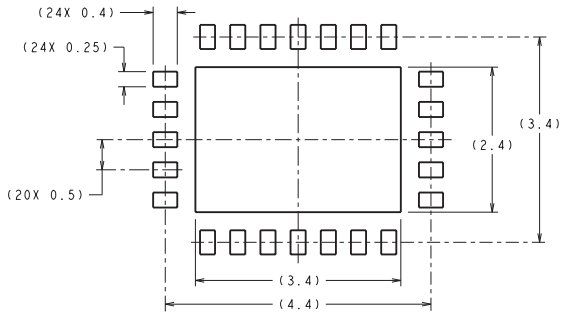
TAPE AND REEL BOX DIMENSIONS



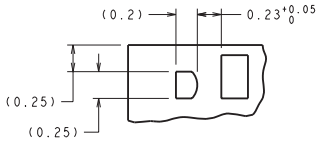
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM64CILQ-F/NOPB	WQFN	NHW	24	1000	213.0	191.0	55.0

NHW0024B

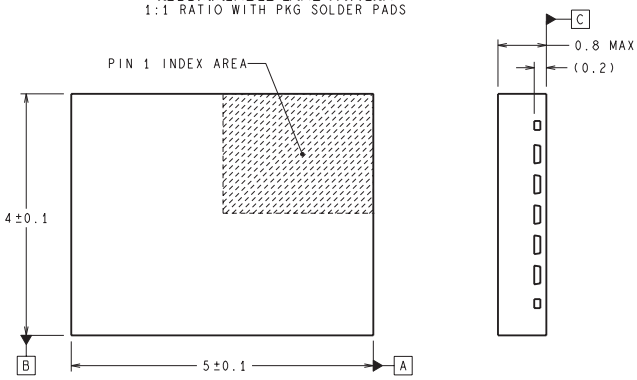


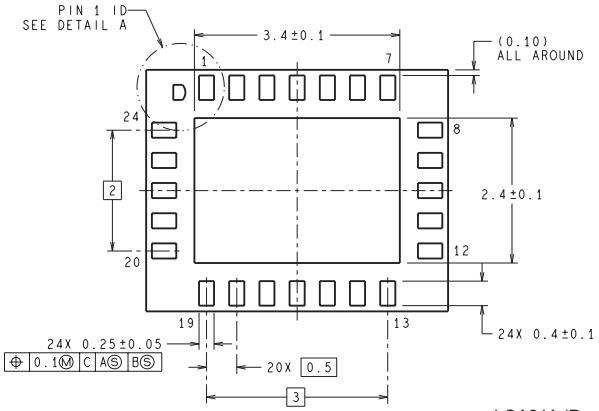
RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS



DETAIL A

DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN ( ) FOR REFERENCE ONLY





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